

An Investigation of a Direct Attach Copper Cable (DAC) Assembly Channel Simulation

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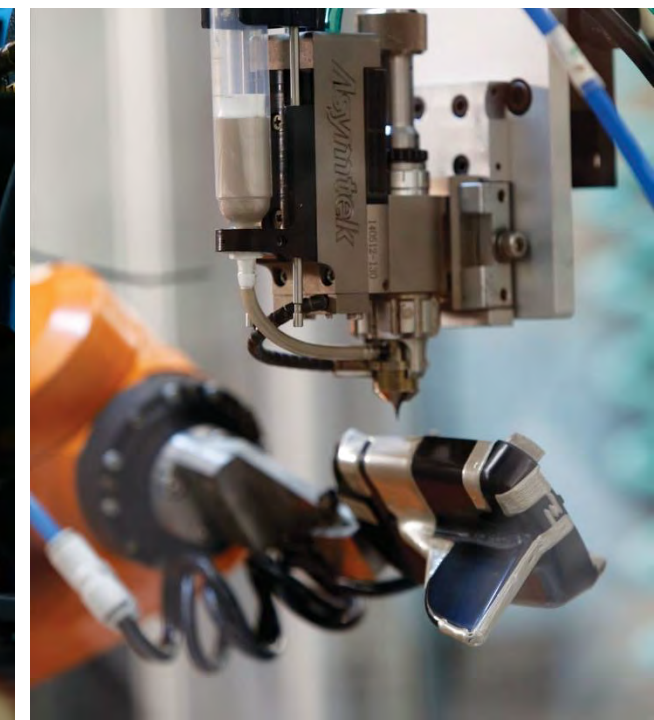
Megha Shanbhag

Matt Schumacher

TE Connectivity

3/22/22

EVERY CONNECTION COUNTS



Overview

A preliminary investigation of a passive copper cable assembly concept channel is presented to help guide P802.3df architecture discussions. Development work is on-going, and updates are expected.

Further detail, refinement and optionality is anticipated in future contributions

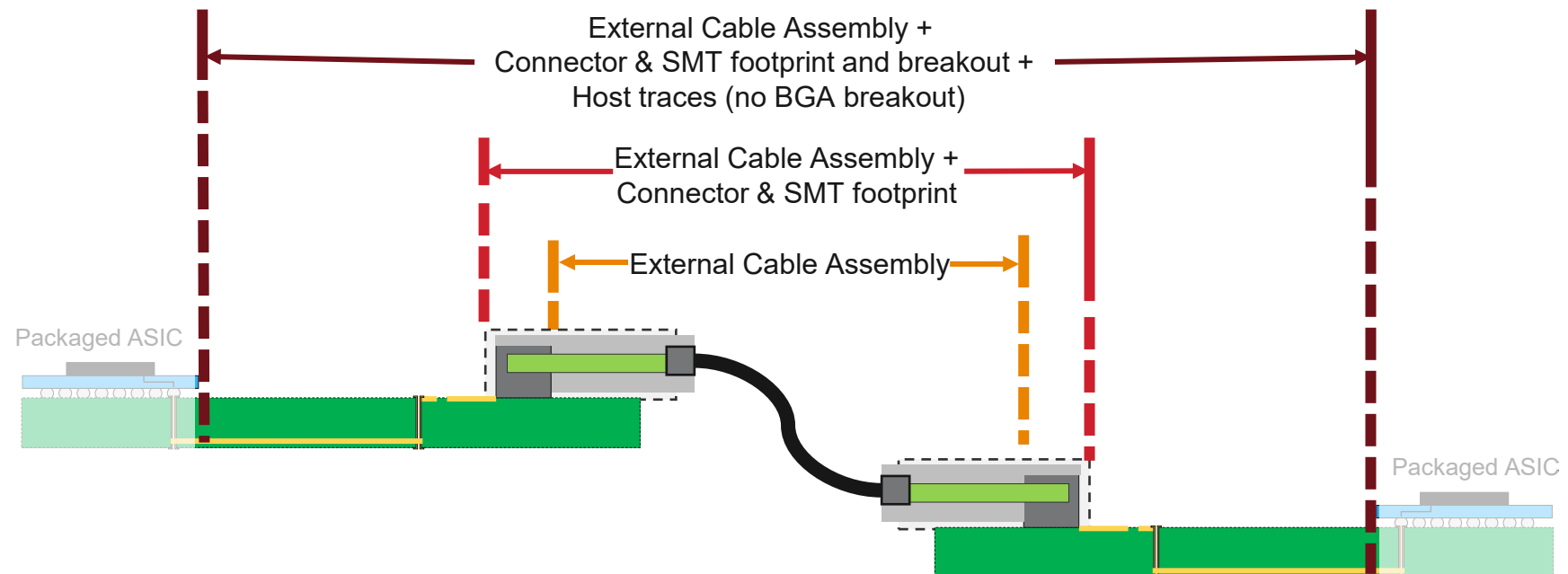
This is not intended to be a final position on a copper cable assembly channel performance

The intent of this presentation is to provide directional input at this early stage of the project

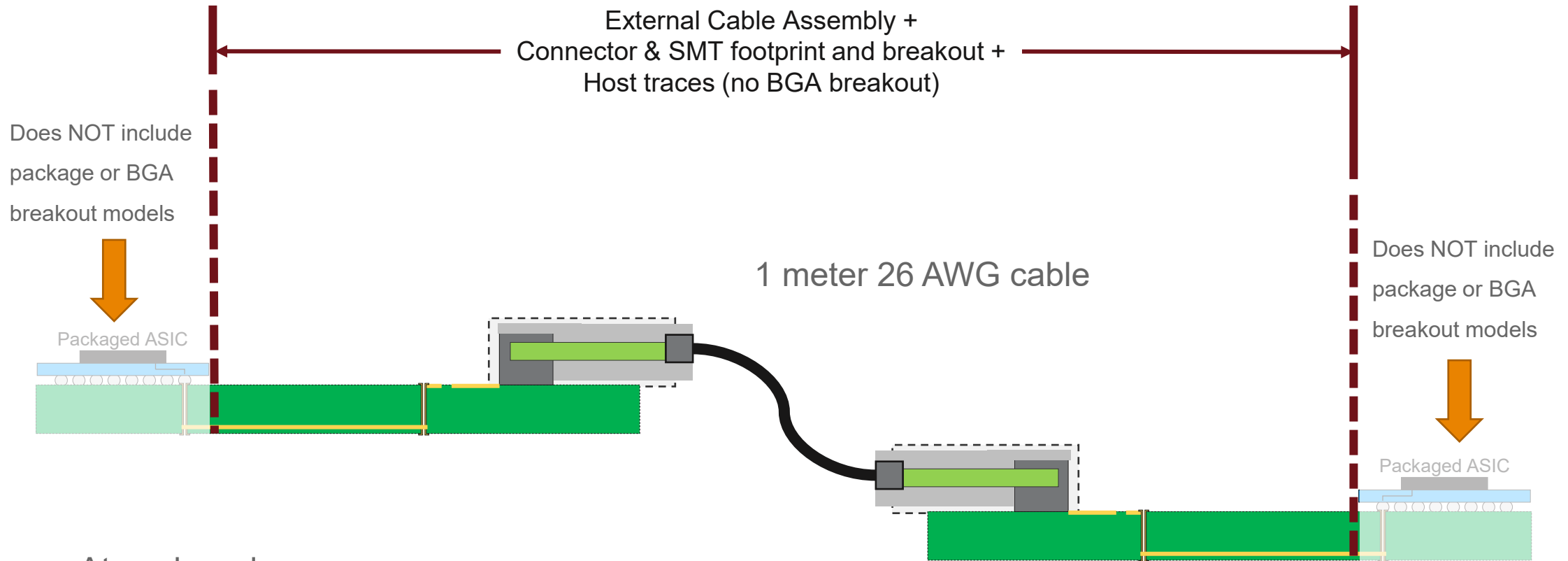
Additional development is in process on connector, bulk cable, wire termination and cable assembly PCB designs

Description

- Simulation for 200G concept connector and cable assembly with host loss
- No silicon package
- No BGA escape. Recommend that BGA escape simulations are contributed for comparative channel evaluations
- Current view of passive cable assembly performance
- What this presentation is NOT:
 - Modulation proposal
 - Host architecture proposal options, i.e. traces vs. cabled host to “near ASIC” vs. co-package copper
 - Asymmetric architectures (managed deployment)



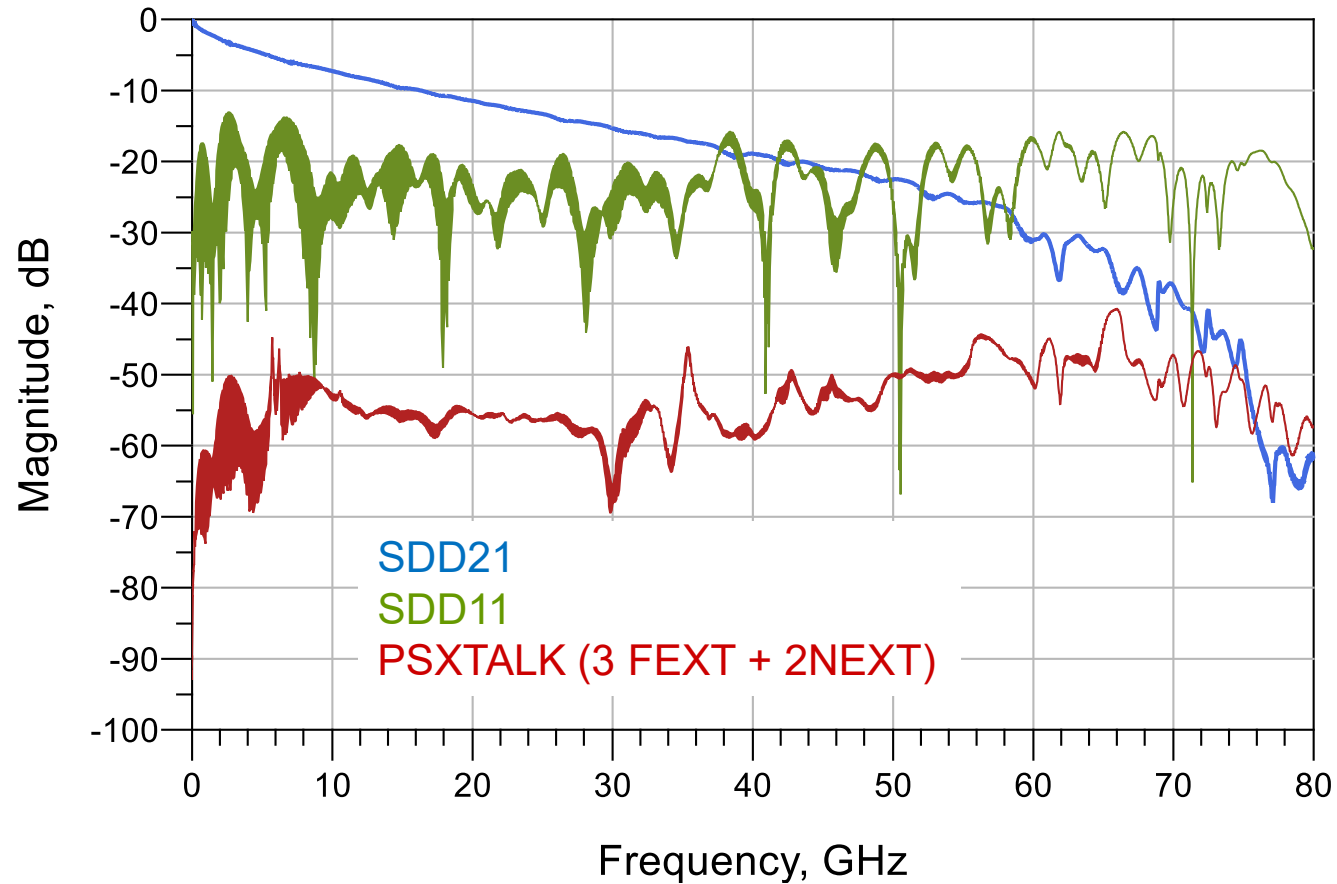
System Topology



At each end,

- OSFP 200G Connector
- Host SMT Footprint
- Host Transition Vias and Conn Breakout
- Host Trace Loss = 5dB @ 53.125 Ghz
- NO BGA BREAKOUT

Channel Performance (No BGA breakout included)



Parameters	@ 42.5 GHz PAM-6	@ 53.125 GHz PAM-4
Insertion Loss	20.36	25.17
Return Loss	17.58	17.81
Power Sum Crosstalk	50.76	50.93

Test Case	Channel IL @ 53.125GHz	Channel + PKG IL @ 53.125GHz	COM	ERL
1	25.17	30.27	4.7	17.81
2	25.17	31.8	4.54	17.81
3	25.17	35.63	3.58	17.81
4	25.17	37.68	3.05	17.81

Note that ERL/COM results do not capture impact of BGA breakout

Upper → G S S G L L L L G S S G S S G
 Lower → G S S G L L L L G S S G S S G

G: ground contact
 S: high speed contact
 L: low speed contact
 : Victim pair

Script: COM_370BetaL
 Config File on Slide 6

COM Config File

This is just a starting point config file used for this study. It is not a proposal or recommendation.

Table 93A-1 parameters			2	I/O control			Table 93A-3 parameters		
Parameter	Setting	Units	Information				Parameter	Setting	Units
f_b	106.25	GBd		DIAGNOSTICS	1	logical	package_tl_gamma0_a1_a2	[0 0.0009909 0.0002772]	
f_min	0.05	GHz		DISPLAY_WINDOW	0	logical	package_tl_tau	6.14E-03	ns/mm
Delta_f	0.01	GHz		CSV_REPORT	1	logical	package_Z_c	[87.5 87.5 ; 92.5 92.5]	Ohm
C_d	0.4e-4 0.9e-4 1.1e-4 ; 0.4e-4 0.9e-4 1.1e-4	nF	[TX RX]	RESULT_DIR	.\results\200G_kR_{date}\				
L_s	[.12 .15 .14 ; .12 .15 .14]	nH	[TX RX]	SAVE_FIGURES	0	logical			
C_b	[.3e-4 .3e-4]	nF	[TX RX]	Port Order	[1 3 2 4]				
z_p select	[1 2 3 4]		[test cases to run]	RUNTAG	R200_eval				
z_p (TX)	[11 15 26 31; 1.0 1.0 1.0 1.0]	mm	[test cases]	COM_CONTRIBUTION	0	logical			
z_p (NEXT)	[9 15 24 29; 1.0 1.0 1.0 1.0]	mm	[test cases]	Operational			Table 92-12 parameters		
z_p (FEXT)	[11 15 26 31; 1.0 1.0 1.0 1.0]	mm	[test cases]	COM Pass threshold	3	dB	board_tl_gamma0_a1_a2	[0 6.44084e-4 3.6036e-05]	1.5 dbpi at 56G
z_p (RX)	[9 15 24 29; 1.0 1.0 1.0 1.0]	mm	[test cases]	ERL Pass threshold	10.5	dB	board_tl_tau	0.00579	ns/mm
C_p	[0.4e-4 0.4e-4]	nF	[TX RX]	DER_0	7.00E-04		board_Z_c	100	Ohm
R_0	50	Ohm		T_r	2.50E-03	ns	z_bp (TX)	50	mm
R_d	[50 50]	Ohm	[TX RX]	FORCE_TR	1	logical	z_bp (NEXT)	50	mm
A_v	0.413	V		Local Search	2		z_bp (FEXT)	50	mm
A_fe	0.413	V					z_bp (RX)	50	mm
A_ne	0.608	V		TDR and ERL options			C_0	[0.2e-4]	nF
L	4			TDR	1	logical	C_1	[0.1e-4]	nF
M	32			ERL	1	logical	Include PCB	0	logical
filter and Eq				ERL_ONLY	0	logical	Floating Tap Control		
f_r	0.5	*fb		ERL_PASS	0.01	ns	N_bg	4	0 1 2 or 3 groups
c(0)	0.55		min	TR_TDR	6000		N_bf	6	taps per group
c(-1)	[-0.34:0.02:0]		[min:step:max]	N	0.618		N_f	80	UI span for floating taps
c(-2)	[0:0.02:0.2]		[min:step:max]	beta_x	0		bmaxg	0.2	max DFE value for floating taps
c(-3)	[-0.1:0.02: 0]		[min:step:max]	rho_x	0		B_float_RSS_MAX	0.2	rss tail tap limit
c(1)	[-0.1:0.02:0]		[min:step:max]	fixture delay time	[0 0]	port1 port2]	N_tail_start	25	(UI) start of tail taps limit
N_b	12	UI		TDR_W_TXPKG	0		ICN parameters		
b_max(1)	0.9			N_bx	36	UI	f_v	0.890	*Fb
b_max(2..N_b)	0.3			Z_t	50	ohm	f_f	5*4	*Fb
b_min(1)	-0.85			Receiver testing			f_n	5*4	*Fb
b_min(2..N_b)	-0.3			RX_CALIBRATION	0	logical	f_2	53.125	GHz
g_DC	[-20:1:0]	dB	[min:step:max]	Sigma BBN step	5.00E-03	V	A_ft	0.600	V
f_z	42.5	GHz		Noise, jitter			A_nt	0.600	V
f_p1	42.5	GHz		sigma_RJ	0.01	UI	Dynamic TXFFE		
f_p2	106.25	GHz		A_DD	0.02	UI	FloatingDFE_Development		
g_DC_HP	[-8:1:0]		[min:step:max]	eta_0	2.10E-09	V^2/GHz			
f_HP_PZ	1.0625	GHz		SNR_TX	34	dB			
				R_LM	0.95				

- Simulation results have been provided for a 200G channel consisting of:
 - 1m DAC 200G concept cable assembly
 - OSFP 200G concept connector (x 2)
 - Host connector footprint and via (x 2)
 - 5 dB of host loss @53.125 Ghz (x 2)
- Not a final position on performance, on-going work, additional optional implementations anticipated
- No position has been taken on modulation scheme for CR applications
- Intent is to provide guidance input for 802.3df architecture discussions

